

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	BSZ0704LS	**Issued**	02. June 2021
MA#	MA001689046		
Package	PG-TSDSON-8-25	**Weight***	35.42 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.281	0.79	0.79	7940	7940
leadframe	inorganic material	phosphorus	7723-14-0	0.002	0.01		69	
	non noble metal	zinc	7440-66-6	0.010	0.03		278	
	non noble metal	iron	7439-89-6	0.197	0.56		5554	
	non noble metal	copper	7440-50-8	7.988	22.55	23.15	225516	231417
wire	noble metal	gold	7440-57-5	0.030	0.08	0.08	839	839
encapsulation	organic material	carbon black	1333-86-4	0.038	0.11		1077	
	plastics	epoxy resin	-	1.965	5.55		55475	
	inorganic material	silicondioxide	60676-86-0	17.075	48.20	53.86	482036	538588
leadfinish	non noble metal	tin	7440-31-5	0.395	1.12	1.12	11159	11159
plating	noble metal	silver	7440-22-4	0.020	0.06	0.06	574	574
solder	non noble metal	tin	7440-31-5	0.009	0.03		264	
	noble metal	silver	7440-22-4	0.012	0.03		330	
	non noble metal	lead	7439-92-1	0.447	1.26	1.32	12621	13215
heatspreader	inorganic material	phosphorus	7723-14-0	0.001			33	
	non noble metal	zinc	7440-66-6	0.005	0.01		133	
	non noble metal	iron	7439-89-6	0.094	0.27		2653	
	non noble metal	copper	7440-50-8	3.816	10.77	11.05	107725	110544
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.001			26	
	non noble metal	zinc	7440-66-6	0.004	0.01		103	
	non noble metal	iron	7439-89-6	0.073	0.21		2057	
	non noble metal	copper	7440-50-8	2.959	8.35	8.57	83538	85724
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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